

Ratings Maximum operating voltage: 48 V **Connector Current Capacity** Maximum operating current: 6.0 A (not mated under load) 9.0 Operating Temperature Range -25 ~ 85 °C, relative humidity of 85% or less 8.0 Materials Max Current (1)Insulator: PBT, black 2)Cover: PBT, black 7.0 Ŷ (3)Terminal: brass, silver plated (4)Terminal: brass, silver plated Upper Temperature Limit 85 Operating Current 6.0 (5)Spring contact: phosphor bronze, silver plated Current (Amps) 0.5 (6)Center Pin: copper alloy, nickel plated **Electrical Requirements** Dielectric strength: 1 min @ 500 Vac Insulation resistance: 100 MΩ @ 500 Vdc minimum Contact resistance: 50 mQ maximum **Mechanical Requirements** (Derated) Insertion force: 0.7-1.5 kaf 3.0 Withdrawal force: 0.5-1.5 kgf Operating Life cycle: 5000 mating cycles while maintaining contact Area resistance: 100 mΩ maximum, withstand voltage: 500 Vac, 1 min 2.0 Terminal strength: 150 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and without damage or excessive looseness of terminals 1.0 Soldering Solderability: 75% minimum coverage when terminals dipped 2mm in 245 \pm 5 °C solder bath for 3 \pm 0.5 seconds 0.0 Solder bath durability: no deformation when immersed in 255 ±5 °C 35.0 45.0 55.0 65.0 85.0 75.0 95.0 up to surface of the board 1.6 mm for 5 seconds or less Ambient Temperature (°C) Solder iron durability: no deformation when exposed to 350 ±10 °C for 3 ±0.5 seconds Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, and does not take into account external factors such as housings,mating cables, or other circuitry. Operating current curve **Environmental Requirements** (derated by 20% of maximum values) accounts for external factors, and manufacturing variation. Cold test: -25 ±3 °C for 48 hours without deformation Heat test: 85 ±2 °C, relative humidity 45-85% for 48 hours without deformation **Wave Soldering Temperature Profile** Humidity test: 40 ±2 °C, relative humidity 90-95% for 48 hours 245 °C peak (5 seconds max) without deformation Temperature (°C) Pb - Free Flow Profile Solder temperature: 245 °C 120 °C Time: 5 seconds maximum Pre-heat: 100 ~120°C 100 °C Time: 70 seconds maximum Pre-heat Measure point: surface of the solder leads 70 seconds (max) Time (S) Date: Description: Revision: Prepared: Notes: Digitally signed by RS Date: 2018.09.27 16:37:30 -07'00' TENSILITY RS А 9/26/2018 Initial release Function test: no open, no short circuit, no intermittent Verified: Digitally signed by AG Date: 2018.09.27 16:38:35 -07'00' tel 1.541.323.3228 800 877.670.7118 AG fax 1.541.323.4202 web tensility.com

Dimensions are in	
millimeters. Tolerances:	Description:
< 1.0: ± 0.1 mm	Connector, dc jack 5.5x2.1 mm, PCB mount, 90°,
1.0 to 10.0: ± 0.2 mm	silver plated, board lock
> 10.0: ± 0.3 mm	

5

3

2

Size:

А

Scale: 5:1

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Sheet 2 of 2

Part number:

54-00131